IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:)
Wu et al.) Group Art Unit: 2891
Serial No.: 10/672,778) Examiner: Smith, Bradley
Filed: September 26, 2003) Confirmation No.: 9717
For: Atomic Layer Deposition (ALD) Method with Enhanced Deposition Rate	TKHR Docket: 252016-3000 Top-Team: 0503-8501DUS

The Ender

RESPONSE TO FINAL OFFICE ACTION

Mail Stop AF

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Sir

The FINAL Office Action mailed May 19, 2006 has been carefully considered. In further response thereto, please enter the following amendments and consider the following remarks.